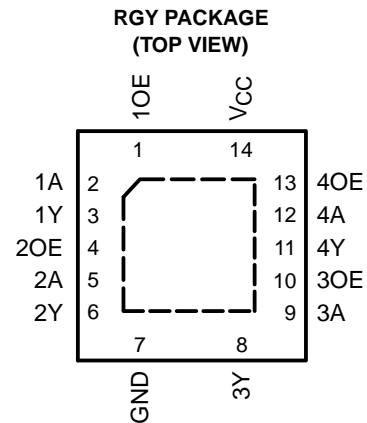


FEATURES

- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- I_{off} Supports Partial-Power-Down Mode Operation
- Sub 1-V Operable
- Max t_{pd} of 2.1 ns at 1.8 V
- Low Power Consumption, 10- μ A Max I_{CC}
- ± 8 -mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1500-V Charged-Device Model (C101)



DESCRIPTION/ORDERING INFORMATION

This quadruple bus buffer gate is designed for 0.8-V to 2.7-V V_{CC} operation, but is designed specifically for 1.6-V to 1.95-V V_{CC} operation.

The SN74AUC126 contains four independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (OE) input is low.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74AUC126RGYR	MS126

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS		OUTPUT
OE	A	Y
H	H	H
H	L	L
L	X	Z

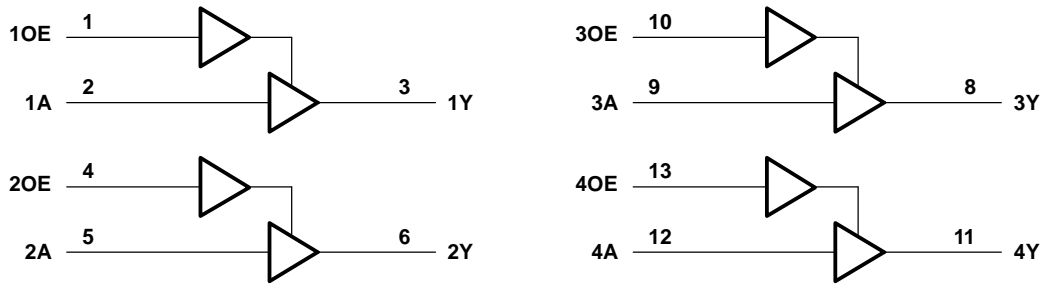


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SN74AUC126
QUADRUPLE BUS BUFFER GATE
WITH 3-STATE OUTPUTS

SCES509–NOVEMBER 2003–REVISED DECEMBER 2005

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	3.6	V
V_I	Input voltage range ⁽²⁾	-0.5	3.6	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	3.6	V
V_O	Output voltage range ⁽²⁾	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$	-50	mA
I_{OK}	Output clamp current	$V_O < 0$	-50	mA
I_O	Continuous output current		± 20	mA
	Continuous current through V_{CC} or GND		± 100	mA
θ_{JA}	Package thermal impedance ⁽³⁾		47	$^{\circ}\text{C}/\text{W}$
T_{stg}	Storage temperature range	-65	150	$^{\circ}\text{C}$

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-5.

Recommended Operating Conditions⁽¹⁾

		MIN	MAX	UNIT	
V_{CC}	Supply voltage	0.8	2.7	V	
V_{IH}	High-level input voltage	$V_{CC} = 0.8\text{ V}$	V_{CC}	V	
		$V_{CC} = 1.1\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$		
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7		
V_{IL}	Low-level input voltage	$V_{CC} = 0.8\text{ V}$	0	V	
		$V_{CC} = 1.1\text{ V to }1.95\text{ V}$	$0.35 \times V_{CC}$		
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0.7		
V_I	Input voltage	0	3.6	V	
V_O	Output voltage	Active state	0	V_{CC}	V
		3-state	0	3.6	
I_{OH}	High-level output current	$V_{CC} = 0.8\text{ V}$	-0.7	mA	
		$V_{CC} = 1.1\text{ V}$	-3		
		$V_{CC} = 1.4\text{ V}$	-5		
		$V_{CC} = 1.65\text{ V}$	-8		
		$V_{CC} = 2.3\text{ V}$	-9		
I_{OL}	Low-level output current	$V_{CC} = 0.8\text{ V}$	0.7	mA	
		$V_{CC} = 1.1\text{ V}$	3		
		$V_{CC} = 1.4\text{ V}$	5		
		$V_{CC} = 1.65\text{ V}$	8		
		$V_{CC} = 2.3\text{ V}$	9		
$\Delta t/\Delta v$	Input transition rise or fall rate		20	ns/V	
T_A	Operating free-air temperature	-40	85	°C	

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74AUC126 QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

SCE509–NOVEMBER 2003–REVISED DECEMBER 2005

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}	I _{OH} = -100 μA	0.8 V to 2.7 V	V _{CC} - 0.1			V
	I _{OH} = -0.7 mA	0.8 V	0.55			
	I _{OH} = -3 mA	1.1 V	0.8			
	I _{OH} = -5 mA	1.4 V	1			
	I _{OH} = -8 mA	1.65 V	1.2			
	I _{OH} = -9 mA	2.3 V	1.8			
V _{OL}	I _{OL} = 100 μA	0.8 V to 2.7 V	0.2			V
	I _{OL} = 0.7 mA	0.8 V	0.25			
	I _{OL} = 3 mA	1.1 V	0.3			
	I _{OL} = 5 mA	1.4 V	0.4			
	I _{OL} = 8 mA	1.65 V	0.45			
	I _{OL} = 9 mA	2.3 V	0.6			
I _I	V _I = V _{CC} or GND	0 to 2.7 V	±5			μA
I _{off}	V _I or V _O = 2.7 V	0	±10			μA
I _{OZ}	V _O = V _{CC} or GND	2.7 V	±10			μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	0.8 V to 2.7 V	10			μA
C _i	V _I = V _{CC} or GND	2.5 V	2.5			pF
C _o	V _O = V _{CC} or GND	2.5 V	5			pF

(1) All typical values are at T_A = 25°C.

Switching Characteristics

over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 0.8 V	V _{CC} = 1.2 V ± 0.1 V		V _{CC} = 1.5 V ± 0.1 V		V _{CC} = 1.8 V ± 0.15 V			V _{CC} = 2.5 V ± 0.2 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
t _{pd}	A	Y	5.8	0.7	3.7	0.6	2.6	0.5	1	2.1	0.5	1.3	ns
t _{en}	OE	Y	6.2	0.9	3.8	0.7	2.5	0.6	1	2.2	0.6	1.3	ns
t _{dis}	OE	Y	4.3	1.6	4.7	1.5	3.5	1.4	2.4	3.4	1	2.5	ns

Switching Characteristics

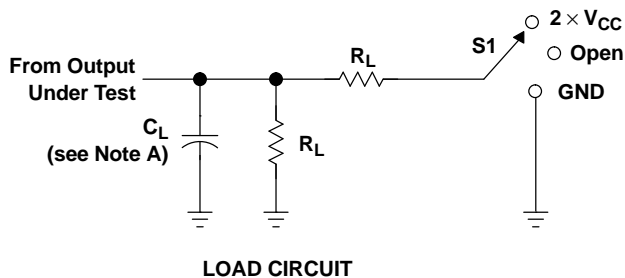
over recommended operating free-air temperature range, C_L = 30 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V			V _{CC} = 2.5 V ± 0.2 V		UNIT
			MIN	TYP	MAX	MIN	MAX	
t _{pd}	A	Y	0.5	1.8	2.6	0.5	2.1	ns
t _{en}	OE	Y	0.6	1.6	2.7	0.6	2.2	ns
t _{dis}	OE	Y	1.2	2.4	3.3	0.8	2.2	ns

Operating Characteristics
 $T_A = 25^\circ\text{C}$

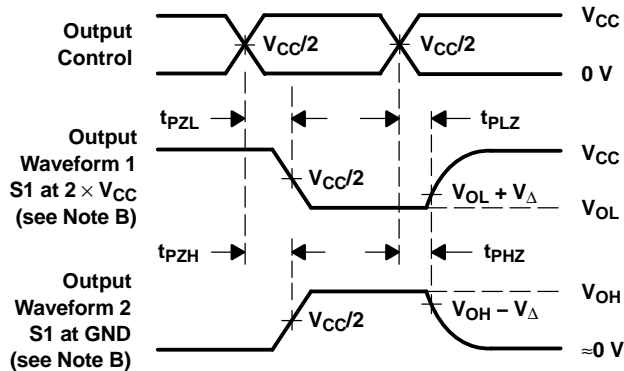
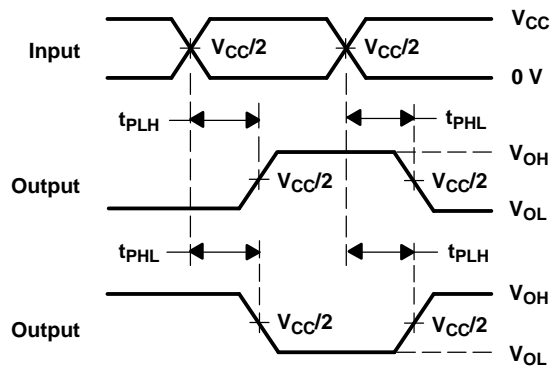
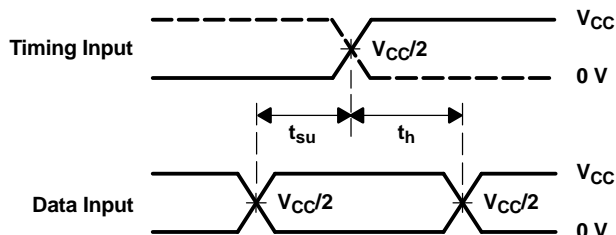
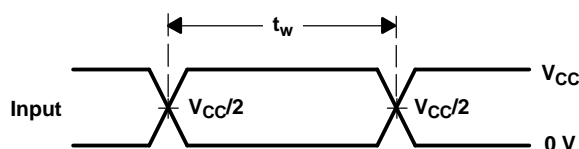
PARAMETER		TEST CONDITIONS	$V_{CC} = 0.8\text{ V}$	$V_{CC} = 1.2\text{ V}$	$V_{CC} = 1.5\text{ V}$	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	UNIT	
			TYP	TYP	TYP	TYP	TYP		
C_{pd}	Power dissipation capacitance	Outputs enabled	f = 10 MHz	15	15	15	16	17	pF
				Outputs disabled	2	2	2	3	

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND

V_{CC}	C_L	R_L	V_{Δ}
0.8 V	15 pF	2 k Ω	0.1 V
1.2 V \pm 0.1 V	15 pF	2 k Ω	0.1 V
1.5 V \pm 0.1 V	15 pF	2 k Ω	0.1 V
1.8 V \pm 0.15 V	15 pF	2 k Ω	0.15 V
2.5 V \pm 0.2 V	15 pF	2 k Ω	0.15 V
1.8 V \pm 0.15 V	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	30 pF	500 Ω	0.15 V



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, slew rate \geq 1 V/ns.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AUC126RGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74AUC126RGYRG4	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUC126RGYR	QFN	RGY	14	1000	180.0	12.4	3.85	3.85	1.35	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUC126RGYR	QFN	RGY	14	1000	190.5	212.7	31.8

RGY (S-PQFP-N14)

PLASTIC QUAD FLATPACK



4203539-2/G 04/2005

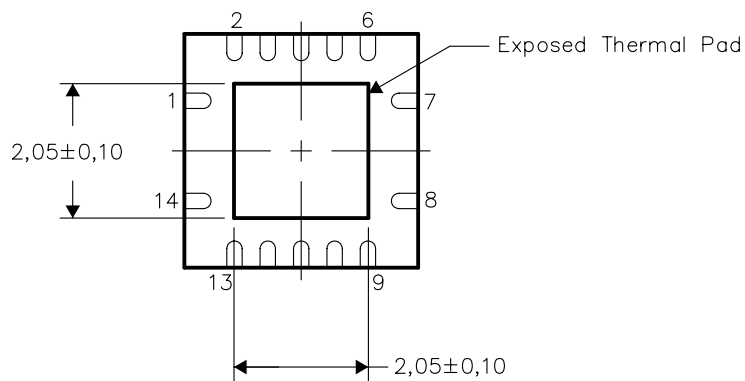
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - E. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - F. Package complies to JEDEC MO-241 variation BA.

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, Quad Flatpack No-Lead Logic Packages, Texas Instruments Literature No. SCBA017. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

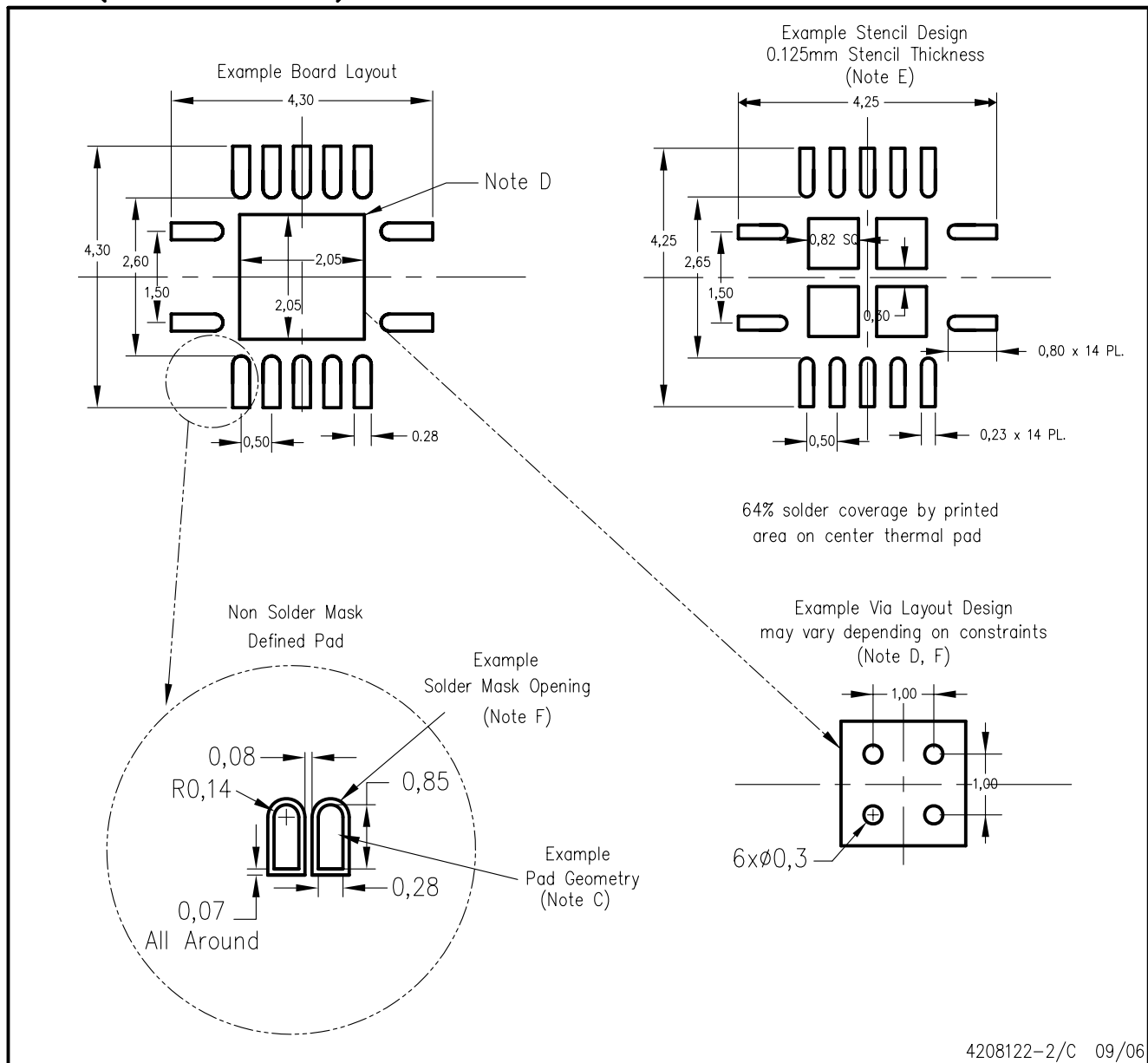


Bottom View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

RGY (R-PQFP-N14)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SCBA017, SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

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